



Docket No.: 213480US0



ATTORNEYS AT LAW

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

RE: Application Serial No.: 09/942,626
Applicants: Sei TSUNODA, et al.
Filing Date: August 31, 2001
For: LOW DIELECTRIC CONSTANT MATERIAL
HAVING THERMAL RESISTANCE, INSULATION
FILM BETWEEN SEMICONDUCTOR LAYERS
USING THE SAME, AND SEMICONDUCTOR
DEVICE
Group Art Unit: 1751
Examiner: VIJAYAKUMAR, K.M.

SIR:

Attached hereto for filing are the following papers:

Amendment Under 37 CFR 1.312;

Copy of Form PTO-1449 as filed August 26, 2005

Our check in the amount of -0- is attached covering any required fees. In the event any variance exists between the amount enclosed and the Patent Office charges for filing the above-noted documents, including any fees required under 37 C.F.R. 1.136 for any necessary Extension of Time to make the filing of the attached documents timely, please charge or credit the difference to our Deposit Account No. 15-0030. Further, if these papers are not considered timely filed, then a petition is hereby made under 37 C.F.R. 1.136 for the necessary extension of time. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,
MAIER & NEUSTADT, P.C.
Norman F. Oblon

Harris A. Pitlick
Registration No. 38,779

Customer Number

22850

(703) 413-3000 (phone)
(703) 413-2220 (fax)

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Dept.:
By: NFO/HAP/scs

Serial No. 09/942,626

In the matter of the Application of: Sei TSUNODA, et al.

For: LOW DIELECTRIC CONSTANT MATERIAL HAVING THERMAL RESISTANCE, INSULATION FILM BETWEEN SEMICONDUCTOR LAYERS USING THE SAME, AND SEMICONDUCTOR DEVICE

Due Date: N/A

The following has been received in the U.S. Patent Office on the date stamped here

- Check for \$180.00
- Dep. Acct. Order Form
- Information Disclosure Statement
- PTO-1449
- Cited References 3
- Japanese Office Action with English translation-in-part



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Dept.: C

By: NFO/HAP/scs

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